



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VB525SP-E	LBK3*V525ABC	A	BOUSKOURA B/E	2016-09-30
Amount		UoM	Unit type	ST ECOPACK Grade
1140.00		mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
CHP	9.5-9.4-3.5	10	FLAT	
Comment	PowerSO 10 POWER 5/SIGNAL SIDE 5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	LBK3*V525ABC									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies (choose)	Other inorganic materials	20.547	mg	supplier	die	Silicon (Si)	7440-21-3		19.997	mg	973231	17540				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.104	mg	5062	91				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.063	mg	3066	55				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	4672	84				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	341	6				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.021	mg	1022	18				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.101	mg	4916	89				
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.158	mg	7690	139				
				supplier	alloy	Copper (Cu)	7440-50-8		629.569	mg	994924	552254				
Leadframe	Copper & its alloys	632.781	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.290	mg	458	254				
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.530	mg	838	465				
				supplier	metallization	Silver (Ag)	7440-22-4		2.392	mg	3780	2098				
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	13.314	mg	954956	11679				
Soft solder	Solder	13.942	mg	supplier	solder	Silver (Ag)	7440-22-4		0.349	mg	25032	306				
				supplier	solder	Tin (Sn)	7440-31-5		0.279	mg	20012	245				
				supplier	wire	Gold (Au)	7440-57-5		1.544	mg	1000000	1354				
Bonding wires	Other inorganic materials	1.544	mg	supplier	wire	Gold (Au)	7440-57-5		1.544	mg	1000000	1354				
				Encapsulation	Other Organic Materials	468.423	mg	supplier	mold compound	Silica, vitreous	60676-86-0		372.397	mg	795000	326664
								supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		39.348	mg	84001	34516
								supplier	mold compound	Phenol resin	9003-35-4		23.421	mg	50000	20545
								supplier	mold compound	Antimony Trioxide	1309-64-4		9.368	mg	19999	8218
								JIG - I	mold compound	Brominated Epoxy Resin	68541-56-0		7.026	mg	14999	6163
								supplier	mold compound	Brominated Epoxy Resin	40039-93-8		5.621	mg	12000	4931
								supplier	mold compound	Bismuth Trioxide	1304-76-3		4.684	mg	10000	4109
supplier	mold compound	Bismuth nitrate	10361-44-1		4.684	mg	10000	4109								
Connections coating	Solder	2.763	mg	supplier	mold compound	carbon black	1333-86-4		1.874	mg	4001	1644				
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.763	mg	1000000	2424				